

PNP MEDIUM POWER TRANSISTORS IN SOT223
Features

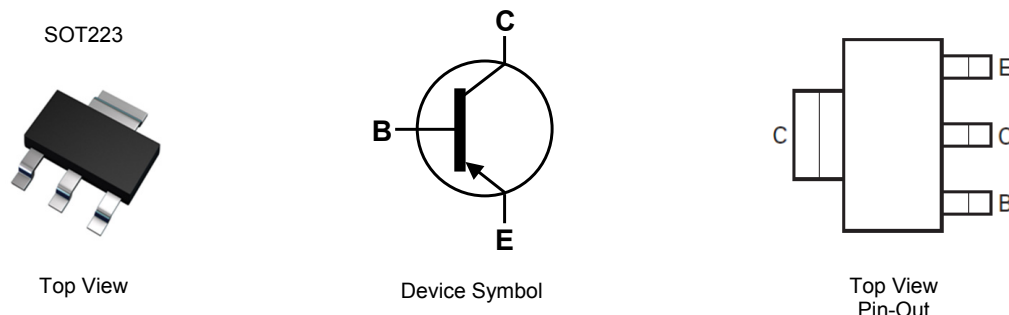
- $BV_{CEO} > -45V, -60V \text{ \& } -80V$
- $I_C = -1A$ High Continuous Collector Current
- $I_{CM} = -2A$ Peak Pulse Current
- 2W Power Dissipation
- Low Saturation Voltage $V_{CE(sat)} < -500mV @ -0.5A$
- Gain Groups 10 and 16
- Complementary NPN types: BCP54, 55 and 56
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.112 grams (approximate)

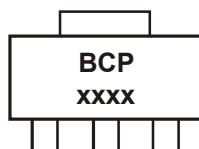
Applications

- Medium Power Switching or Amplification Applications
- AF Driver and Output Stages


Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BCP51TA	AEC-Q101	BCP 51	7	12	1,000
BCP5110TA	AEC-Q101	BCP 5110	7	12	1,000
BCP5116TA	AEC-Q101	BCP 5116	7	12	1,000
BCP5116TC	AEC-Q101	BCP 5116	13	12	4,000
BCP52TA	AEC-Q101	BCP 52	7	12	1,000
BCP5210TA	AEC-Q101	BCP 5210	7	12	1,000
BCP5216TA	AEC-Q101	BCP 5216	7	12	1,000
BCP53TA	AEC-Q101	BCP 53	7	12	1,000
BCP53QTA	Automotive	BCP 53	7	12	1,000
BCP5310TA	AEC-Q101	BCP 5310	7	12	1,000
BCP5316TA	AEC-Q101	BCP 5316	7	12	1,000
BCP5316TC	AEC-Q101	BCP 5316	13	12	4,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
 5. For packaging details, go to our website at <http://www.diodes.com>

Marking Information


BCP = Product Type Marking Code, Line 1.
 xxxx = Product Type Marking Code, Line 2 as follows:

BCP51 = 51	BCP52 = 52	BCP53 = 53
BCP5110 = 5110	BCP5210 = 5210	BCP5310 = 5310
BCP5116 = 5116	BCP5216 = 5216	BCP5316 = 5316

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	BCP51	BCP52	BCP53	Unit
Collector-Base Voltage	V _{CBO}	-45	-60	-100	V
Collector-Emitter Voltage	V _{CEO}	-45	-60	-80	V
Emitter-Base Voltage	V _{EBO}	-5			V
Continuous Collector Current	I _C	-1			A
Peak Pulse Collector Current	I _{CM}	-2			
Continuous Base Current	I _B	-100			mA
Peak Pulse Base Current	I _{BM}	-200			

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

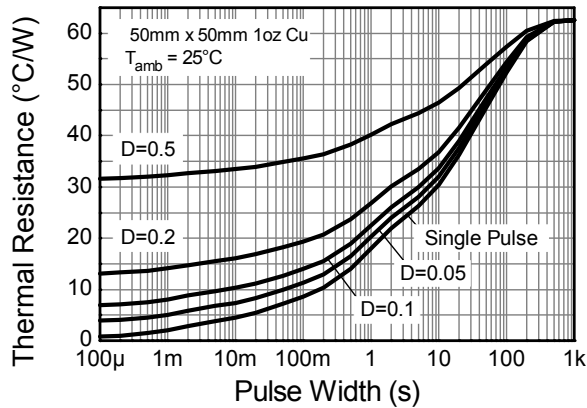
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	2	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	62	°C/W
Thermal Resistance, Junction to Leads (Note 7)	R _{θJL}	19.4	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

ESD Ratings (Note 8)

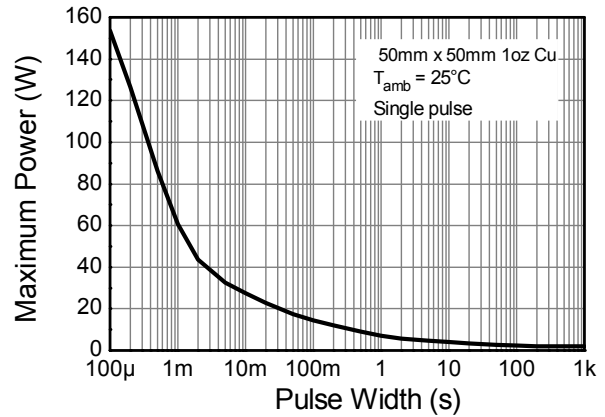
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	≥ 4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	C

- Notes:
6. For a device surface mounted on 50mm X 50mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; device measured when operating in steady state condition.
 7. Thermal resistance from junction to solder-point (at the end of the collector lead).
 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

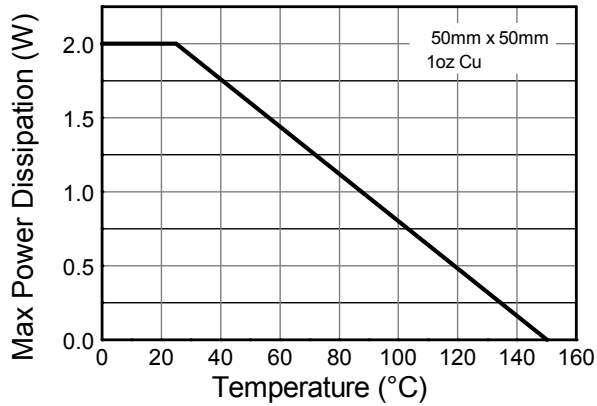
Thermal Characteristics and Derating Information



Transient Thermal Impedance



Pulse Power Dissipation

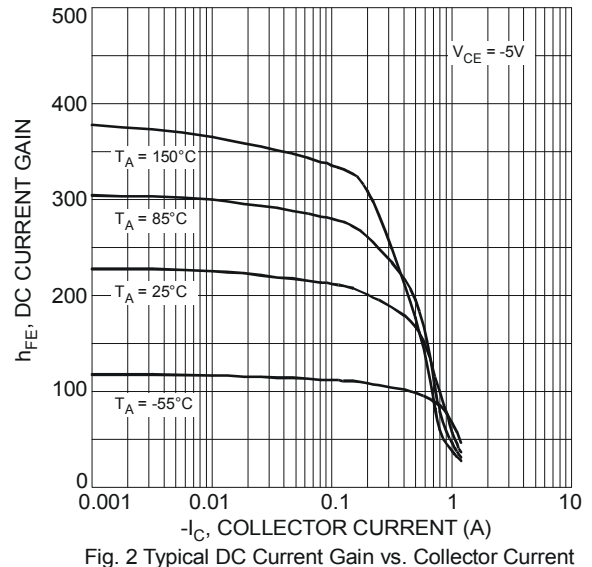
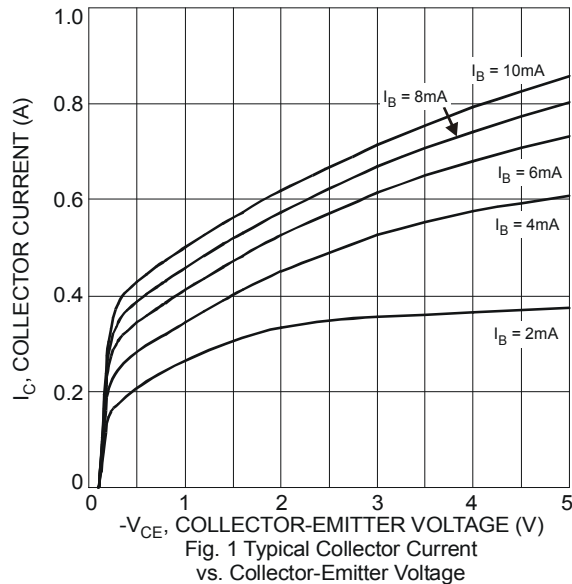


Derating Curve

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BCP51	BV _{CBO}	-45	-	-	V	I _C = -100μA
	BCP52		-60				
	BCP53		-100				
Collector-Emitter Breakdown Voltage (Note 9)	BCP51	BV _{CEO}	-45	-	-	V	I _C = -10mA
	BCP52		-60				
	BCP53		-80				
Emitter-Base Breakdown Voltage		BV _{EBO}	-5	-	-	V	I _E = -10μA
Collector Cut-off Current		I _{CBO}	-	-	-0.1 -20	μA	V _{CB} = -30V V _{CB} = -30V, T _A = +150°C
Emitter Cut-off Current		I _{EBO}	-	-	-20	nA	V _{EB} = -4V
Static Forward Current Transfer Ratio (Note 9)	All versions	h _{FE}	25	-	-	-	I _C = -5mA, V _{CE} = -2V
			40	-	250		I _C = -150mA, V _{CE} = -2V
			25	-	-		I _C = -500mA, V _{CE} = -2V
	10 gain grp		63	-	160		I _C = -150mA, V _{CE} = -2V
	16 gain grp		100	-	250		I _C = -150mA, V _{CE} = -2V
Collector-Emitter Saturation Voltage (Note 9)		V _{CE(sat)}	-	-	-0.5	V	I _C = -500mA, I _B = -50mA
Base-Emitter Turn-On Voltage (Note 9)		V _{BE(on)}	-	-	-1.0	V	I _C = -500mA, V _{CE} = -2V
Transition Frequency		f _r	150	-	-	MHz	I _C = -50mA, V _{CE} = -10V f = 100MHz
Output Capacitance		C _{obo}	-	-	25	pF	V _{CB} = -10V, f = 1MHz

Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.



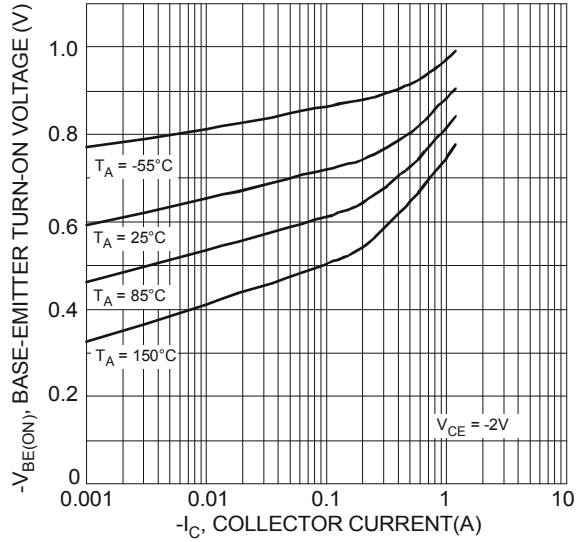


Fig 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

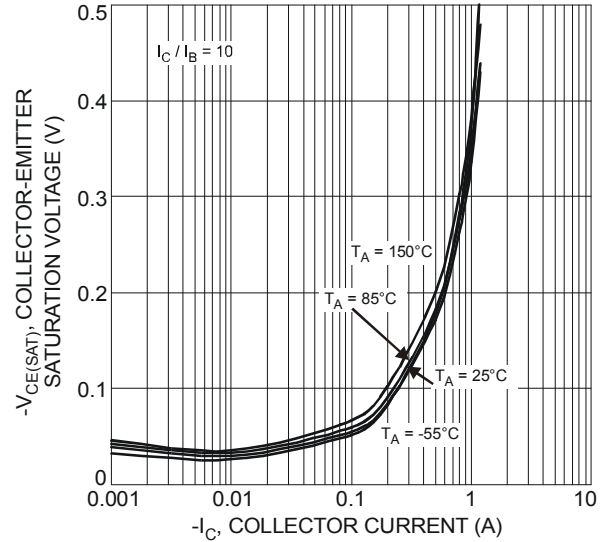


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

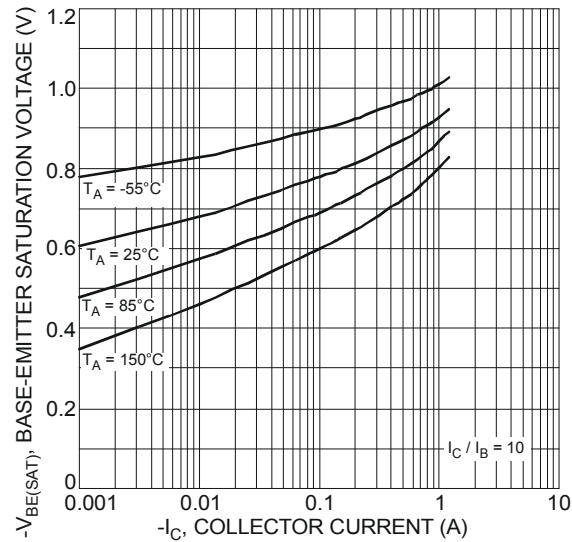


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

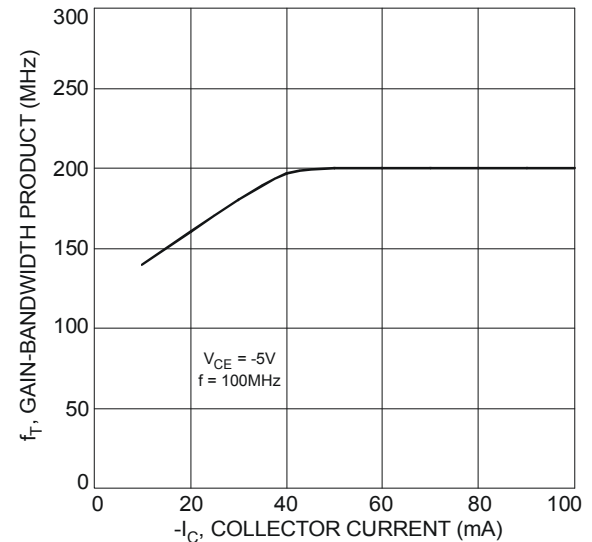


Fig. 6 Typical Gain-Bandwidth Product vs. Collector Current

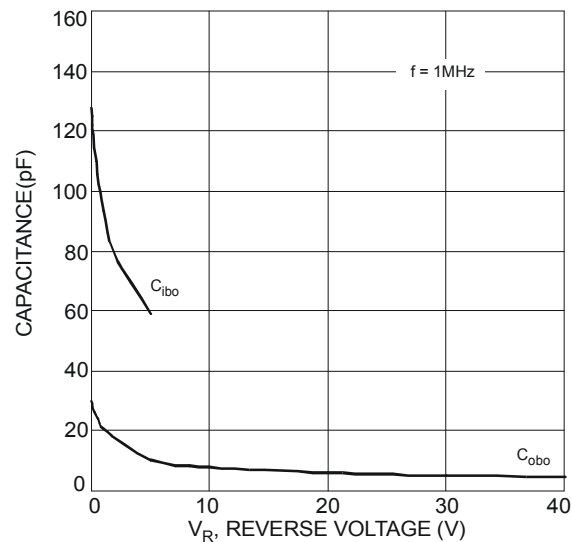
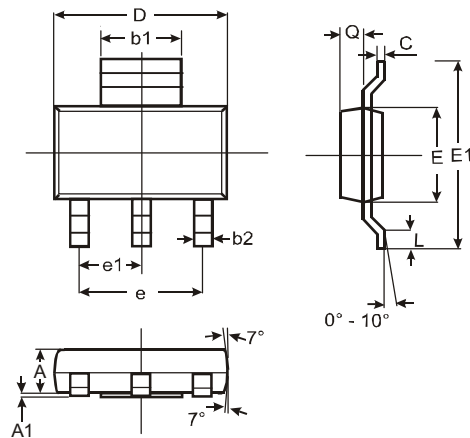


Fig. 7 Typical Capacitance Characteristics

Package Outline Dimensions

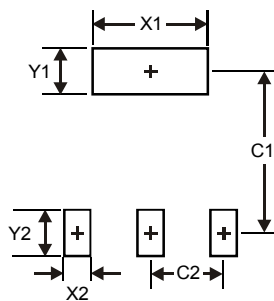
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	—	—	4.60
e1	—	—	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

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